



International cooperation and Eu-Japan Digital Partnership

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DG CONNECT

The EU Chips Act

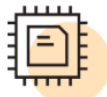
A vision

To jointly create a state-of-the-art European chip ecosystem, that includes a world-class research, production, design and testing capacities.

...and five objectives



- ❑ strengthen its research and technology leadership



- ❑ build and reinforce its own capacity to innovate in the design, manufacturing and packaging of advanced, energy-efficient and secure chips, and turn them into manufactured products



- ❑ put in place an adequate framework to increase substantially its production capacity by 2030



- ❑ address the acute skills shortage, attract new talent and support the emergence of a skilled workforce



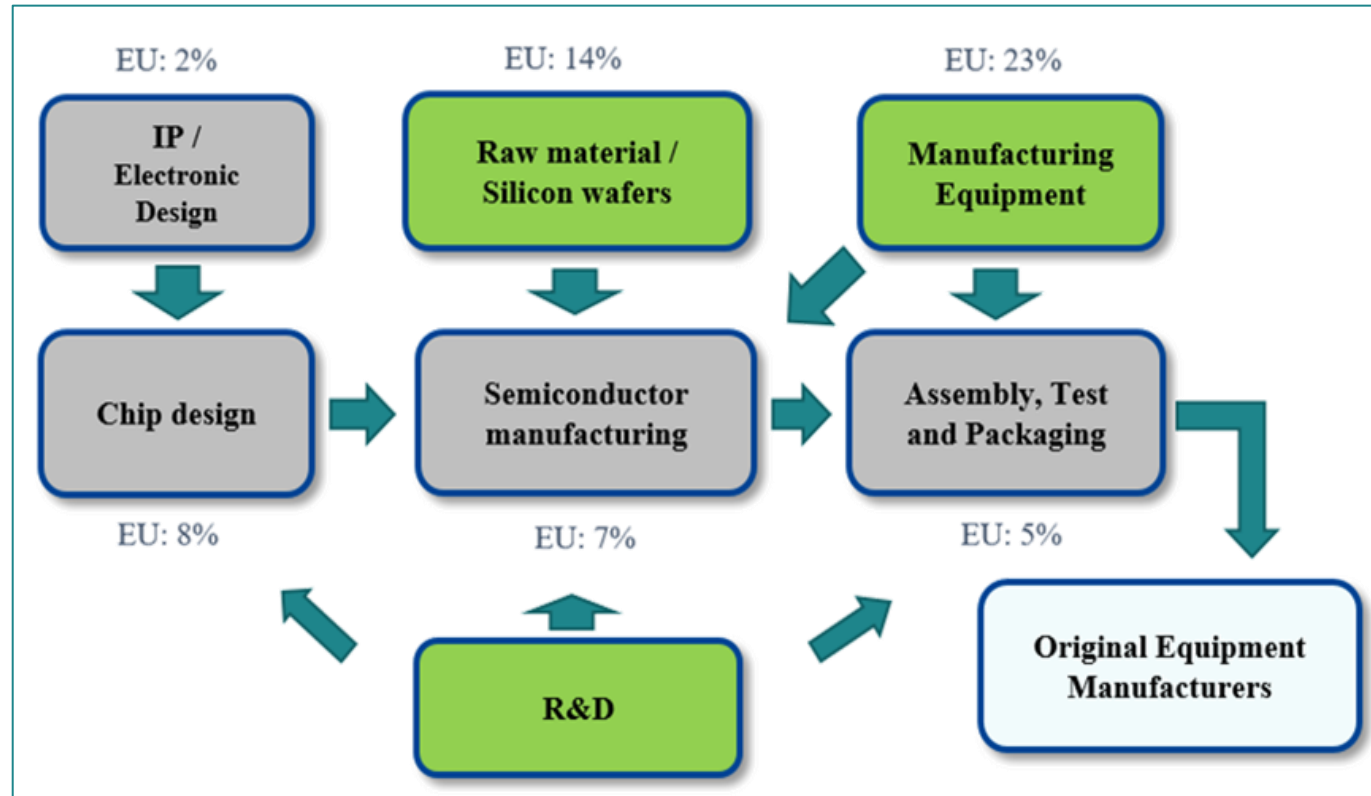
- ❑ develop an in-depth understanding of global semiconductor supply chains and take appropriate measures when necessary



Semiconductor value chain in Europe

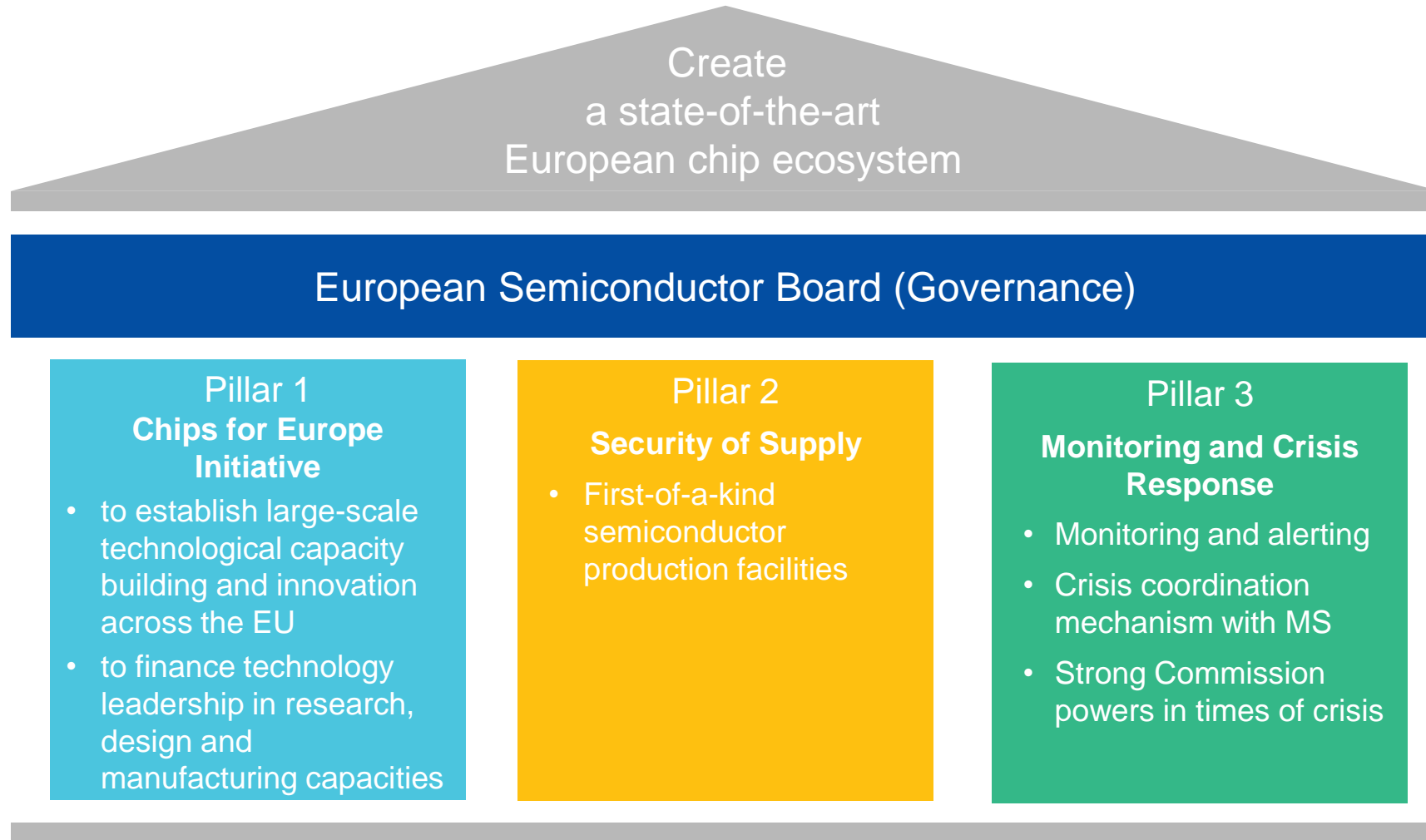


- EU strengths:**
- R&D
 - manufacturing equipment
 - raw materials



- EU gaps:**
- IP & digital design
 - design tools
 - manufacturing
 - packaging

Three pillars of the Chips Act



International Cooperation

- **Trade and Technology Council (TTC) with US**, WG3 Secure Supply chain on semiconductors
- **Digital Partnerships with:**
 - Japan
 - South-Korea
 - Singapore
- **Trade and Technology Council (TTC) with India**, WG1 on Strategic technologies, digital governance and digital connectivity



Japan-EU Digital Partnership

Semiconductors

Strengthen the security and resilience of the global semiconductor supply chain, including by exchanging information on their respective approaches.

Explore joint monitoring and effective early warning mechanisms to anticipate periods of crisis.

Promote research in semiconductor technologies in areas of common interest and mutual benefit

Thank you